

ABSTRACT

A wafer, a method and an apparatus for improving roughness of the wafer, a device and a medium are provided. The method includes: in a case that roughness of a raw wafer obtained through a wire sawing process within a target wavelength range is greater than or equal to a predetermined roughness threshold, determining an index value for representing a wire sawing capability of a currently-used wire sawing slurry based on a geometric similarity between an abrasive particle in the currently-used wire sawing slurry for the wire sawing process and a regular polyhedron; and in a case that the index value is smaller than or equal to a predetermined performance threshold, replenishing a new wire sawing slurry into an equipment for performing the wire sawing process.

(Figure 2)